

WHAT IS CLAIMED IS:

1. An exposure apparatus for transferring a pattern on a master to a substrate via an optical system, comprising:

5 a first housing for surrounding an exposure position of the master;

a second housing for stocking the master; and

a third housing for transferring the master between inside and outside of said first housing,

10 wherein an interior of each housing is controlled to a predetermined atmosphere.

2. The apparatus according to claim 1, wherein the master transferred from the outside of said first housing via said third housing is stocked in said
15 second housing.

3. The apparatus according to claim 1, wherein said third housing includes a load-lock chamber, and

the apparatus further comprises first
20 opening/closing means between the outside of said first housing and the load-lock chamber, and second opening/closing means between the load-lock chamber and the inside of said first housing.

4. The apparatus according to claim 3, wherein in
25 transferring the master from the outside to inside of said first housing, said first opening/closing means is opened, the master is transferred from the outside of

between said alignment means and the exposure position.

11. The apparatus according to claim 1, wherein said first housing has exposure beam transmission ports above and below the exposure position.

5 12. The apparatus according to claim 1, wherein the predetermined atmosphere includes an inert gas atmosphere.

13. The apparatus according to claim 12, wherein the atmosphere is controlled by a circulation system via
10 cleaning means.

14. The apparatus according to claim 12, wherein inert gas for forming the predetermined atmosphere is supplied to the exposure position.

15 15. The apparatus according to claim 12, wherein inert gas for forming the predetermined atmosphere is supplied to a vicinity of said second housing in said first housing.

16. The apparatus according to claim 1, wherein the predetermined atmosphere includes vacuum.

20 17. The apparatus according to claim 1, wherein an exposure light source includes an F₂ excimer laser.

18. An exposure apparatus for transferring a pattern on a master to a substrate via an optical system, comprising:

25 a first housing for surrounding an exposure position of the master;

a second housing for stocking the master;

a third housing for transferring the master
between inside and outside of said first housing;

a display;

a network interface; and

5 a computer for executing network software,

wherein an interior of each housing is controlled
to a predetermined atmosphere, and maintenance
information of the exposure apparatus is communicated
via a computer network.

10 19. The apparatus according to claim 18, wherein the
network software provides on said display a user
interface for accessing a maintenance database provided
by a vendor or user of the exposure apparatus and
connected to an external network outside a factory in
15 which the exposure apparatus is installed, and
information is obtained from the database via the
external network.

20 20. An exposure method of transferring a pattern on a
master to a substrate via an optical system, comprising
the steps of:

arranging a first housing for surrounding an
exposure position of the master, a second housing for
stocking the master before being transferred to the
exposure position, and a third housing for transferring
25 the master between inside and outside of the first
housing; and

controlling an interior of each housing to a

predetermined atmosphere.

21. A semiconductor device manufacturing method comprising steps of:

installing, in a semiconductor manufacturing
5 factory, manufacturing apparatuses for various processes including an exposure apparatus; and

manufacturing a semiconductor device by a plurality of processes using the manufacturing apparatuses,

10 wherein the exposure apparatus has a first housing for surrounding an exposure position of a master,

a second housing for stocking the master, and

a third housing for transferring the master
15 between inside and outside of the first housing, and an interior of each housing is controlled to a predetermined atmosphere.

22. The method according to claim 21, further comprising steps of:

20 connecting the manufacturing apparatuses via a local area network; and

communicating information about at least one of the manufacturing apparatuses between the local area network and an external network outside the
25 semiconductor manufacturing factory.

23. The method according to claim 22, wherein a database provided by a vendor or user of the exposure

apparatus is accessed via the external network, thereby obtaining maintenance information of the exposure apparatus by data communication, or data communication is performed between the semiconductor manufacturing
5 factory and another semiconductor manufacturing factory via the external network, thereby performing production management.

24. A semiconductor manufacturing factory comprising:
manufacturing apparatuses for various processes
10 including an exposure apparatus;
a local area network for connecting said manufacturing apparatuses; and
a gateway for allowing access to an external network outside the factory from said local area
15 network,
wherein information about at least one of said manufacturing apparatuses can be communicated,
the exposure apparatus has
a first housing for surrounding an exposure
20 position of a master,
a second housing for stocking the master, and
a third housing for transferring the master between inside and outside of the first housing, and
an interior of each housing is controlled to a
25 predetermined atmosphere.
25. A maintenance method for an exposure apparatus installed in a semiconductor manufacturing factory,

comprising steps of:

making a vendor or user of the exposure apparatus
provide a maintenance database connected to an external
network outside the semiconductor manufacturing

5 factory;

allowing access to the maintenance database from
the semiconductor manufacturing factory via the
external network; and

transmitting maintenance information accumulated
10 in the maintenance database to the semiconductor
manufacturing factory via the external network,

wherein the exposure apparatus has

a first housing for surrounding an exposure
position of a master,

15 a second housing for stocking the master, and

a third housing for transferring the master
between inside and outside of the first housing, and

an interior of each housing is controlled to a
predetermined atmosphere.

20 26. An exposure apparatus for exposing a substrate to
a pattern of a mask, comprising:

a first housing for surrounding the mask when
exposing; and

a second housing for stocking the mask, said
25 housing being inside of said first housing,

wherein interiors of said first and second
housing are filled by an inert gas or are adopted

evacuation.

27. An exposure apparatus for exposing a substrate to a pattern of a mask, comprising:

5 a first housing for surrounding the mask when exposing; and

10 a second housing for stocking the mask, an interior of said second housing is allowed to communicate to an interior of said first housing means, and the interior of said first housing means is not allowed to communicate to an external,

wherein the interiors of said first and second housing are filled by an inert gas or are adopted evacuation.

28. A semiconductor device manufacturing method
15 comprising steps of:

installing, in a semiconductor manufacturing factory, manufacturing apparatuses for various processes including an exposure apparatus for exposing a substrate to a pattern of a mask; and

20 manufacturing a semiconductor device by a plurality of processes using the manufacturing apparatuses,

25 wherein the exposure apparatus has a first housing for surrounding the mask when exposing; and

a second housing for stocking the mask, said housing being inside of said first housing,

wherein interiors of said first and second housing are filled by an inert gas or are adopted evacuation.

29. A semiconductor device manufacturing method
5 comprising steps of:

installing, in a semiconductor manufacturing factory, manufacturing apparatuses for various processes including an exposure apparatus for exposing a substrate to a pattern of a mask; and

10 manufacturing a semiconductor device by a plurality of processes using the manufacturing apparatuses,

wherein the exposure apparatus has

a first housing for surrounding the mask when
15 exposing; and

a second housing for stocking the mask, an interior of said second housing is allowed to communicate to an interior of said first housing means, and the interior of said first housing means is not
20 allowed to communicate to an external,

wherein the interiors of said first and second housing are filled by an inert gas or are adopted evacuation.